



# Re-classification of VOG8 Moisture Sensitivity Level

XCN06001 (v1.1) March 2, 2006

Customer Notice – FYI

## Overview

The purpose of this notification is to communicate that subjecting the VOG8 package to MSL 1 might cause some delamination on the bond fingers of the lead frame (<10% delamination). The delamination will not cause any electrical failure after pre-conditioning and no long-term reliability failures.

Qualification data for this package using MSL 3 showed no delamination on the bond fingers. The MSL of this package is therefore being re-classified from MSL 1 to MSL 3 per JEDEC STD-020C.

## Description

Moisture-induced delamination on the bond fingers has been observed on the VOG8 package after MSL 1 pre-conditioning. The delamination will not cause any electrical failure after pre-conditioning and no long-term reliability failures.

The VOG8 package that was subjected to MSL 3 pre-conditioning did not show any bond finger delamination. The pre-conditioning was performed per JEDEC STD-020C conditions (192 hours of moisture soaking at 30°C / 60% RH followed by 3X IR reflow at the pb-free peak reflow temperature of 260°C).

Re-classification of this package as MSL 3 means that these devices will have a limited floor lifetime of 168 hours.

## Products Affected

This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade devices. Automotive and Q grade devices are not affected by this Notice. The affected part numbers are included in [Table 1](#).

Table 1: Products Affected

| Devices        |                |
|----------------|----------------|
| XC1736EVOG8C   | XC17S200AVOG8C |
| XC17128EVOG8C  | XC17S10XLVOG8C |
| XC1765ELVOG8C  | XC17S10XLVOG8I |
| XC17S15AVOG8C  | XC17S20XLVOG8C |
| XC17S50AVOG8C  | XC17S30XLVOG8C |
| XC17S100AVOG8C |                |

## Recommendations

Mount the devices on PCB boards within 168 hours after moisture barrier bags are opened (refer to JEDEC-STD-020C).

## Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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## Revision History

The following table shows the revision history for this document.

| Date     | Version | Revision  |
|----------|---------|---|
| 01/16/06 | 1.0     | Initial Xilinx release.   |
| 03/02/06 | 1.1     | Updated <a href="#">Table 1</a> with the complete part numbers that include the “C” and “I” part designators. |